

PMEG2005AEL

0.5 A ultra low V_F MEGA Schottky barrier rectifier in leadless ultra small SOD882 package

Rev. 02 — 27 April 2004

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier diode with an integrated guard ring for stress protection encapsulated in a SOD882 leadless ultra small plastic package.

1.2 Features

- Forward current: 0.5 A
- Reverse voltage: 20 V
- Ultra low forward voltage
- Leadless ultra small plastic package
- Power dissipation comparable to SOT23.

1.3 Applications

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Low voltage rectification
- High efficiency DC-to-DC conversion
- Low power consumption applications.

1.4 Quick reference data

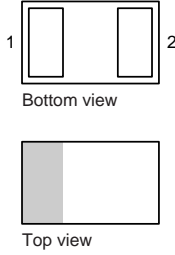

Table 1: Quick reference data

Symbol	Parameter	Value	Unit
I_F	forward current	0.5	A
V_R	reverse voltage	20	V

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2. Pinning information

Table 2: Discrete pinning

Pin	Description	Simplified outline	Symbol
1	cathode	 <p>Bottom view</p> <p>Top view</p> <p>001aaa332</p>	 sym001
2	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3: Ordering information

Type number	Package		
	Name	Description	Version
PMEG2005AEL	-	leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.5 mm	SOD882

4. Marking

Table 4: Marking

Type number	Marking code
PMEG2005AEL	F2

5. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	continuous reverse voltage		-	20	V
I_F	continuous forward current		-	0.5	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ ms; $\delta \leq 0.25$	-	2.5	A
I_{FSM}	non-repetitive peak forward current	$t = 8$ ms square wave	-	3	A
T_j	junction temperature		[1] -	150	°C
T_{amb}	operating ambient temperature		[1] -65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

- [1] For Schottky barrier diodes thermal run-away has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determining the reverse power losses P_R and $I_{F(AV)}$ rating will be available on request.

6. Thermal characteristics

Table 6: Thermal characteristics

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2] 500	K/W

[1] Refer to SOD882 standard mounting conditions (footprint), FR4 with 60 μm copper strip line.

[2] For Schottky barrier diodes thermal run-away has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determining the reverse power losses P_R and $I_{F(AV)}$ rating will be available on request.

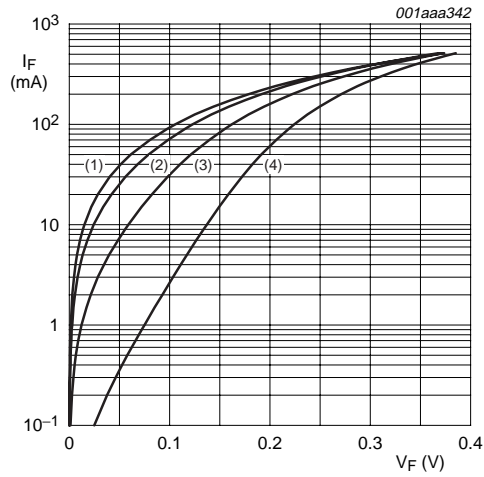
7. Characteristics

Table 7: Characteristics

$T_{amb} = 25^\circ\text{C}$ unless otherwise specified

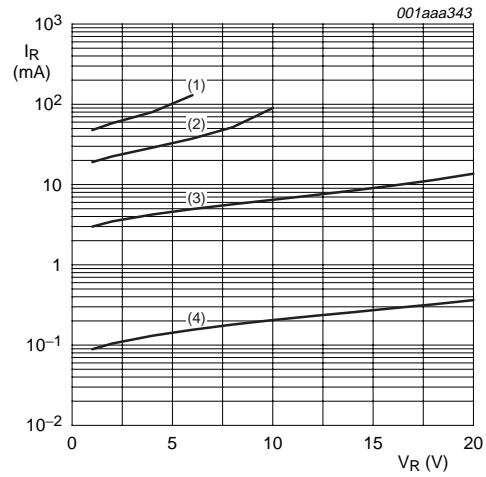
Symbol	Parameter	Conditions	Typ	Max	Unit
V_F	continuous forward voltage	see Figure 1 ;			
		$I_F = 0.1\text{ mA}$	25	60	mV
		$I_F = 1\text{ mA}$	75	110	mV
		$I_F = 10\text{ mA}$	135	190	mV
		$I_F = 100\text{ mA}$	220	290	mV
		$I_F = 500\text{ mA}$	375	440	mV
I_R	continuous reverse current	see Figure 2 ;			
		$V_R = 10\text{ V}$	210	600	μA
		$V_R = 20\text{ V}$	370	1500	μA
C_d	diode capacitance	$V_R = 1\text{ V}$; $f = 1\text{ MHz}$; see Figure 3	19	25	pF

[1] Pulse test: $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$.



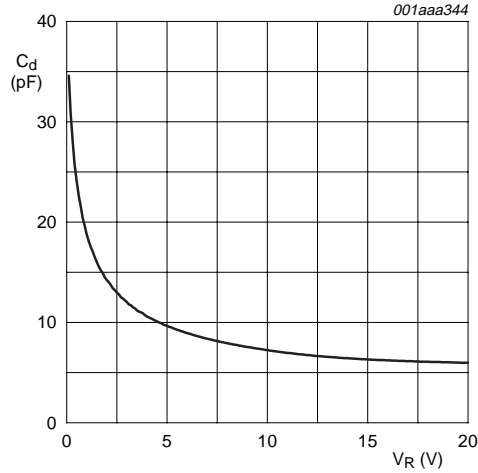
- (1) $T_j = 150\text{ }^\circ\text{C}$.
- (2) $T_j = 125\text{ }^\circ\text{C}$.
- (3) $T_j = 85\text{ }^\circ\text{C}$.
- (4) $T_j = 25\text{ }^\circ\text{C}$.

Fig 1. Forward current as a function of forward voltage; typical values.



- (1) $T_j = 150\text{ }^\circ\text{C}$.
- (2) $T_j = 125\text{ }^\circ\text{C}$.
- (3) $T_j = 85\text{ }^\circ\text{C}$.
- (4) $T_j = 25\text{ }^\circ\text{C}$.

Fig 2. Reverse current as a function of reverse voltage; typical values.



$T_{amb} = 25\text{ }^\circ\text{C}$; $f = 1\text{ MHz}$.

Fig 3. Diode capacitance as a function of reverse voltage; typical values.

8. Package outline

Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

SOD882

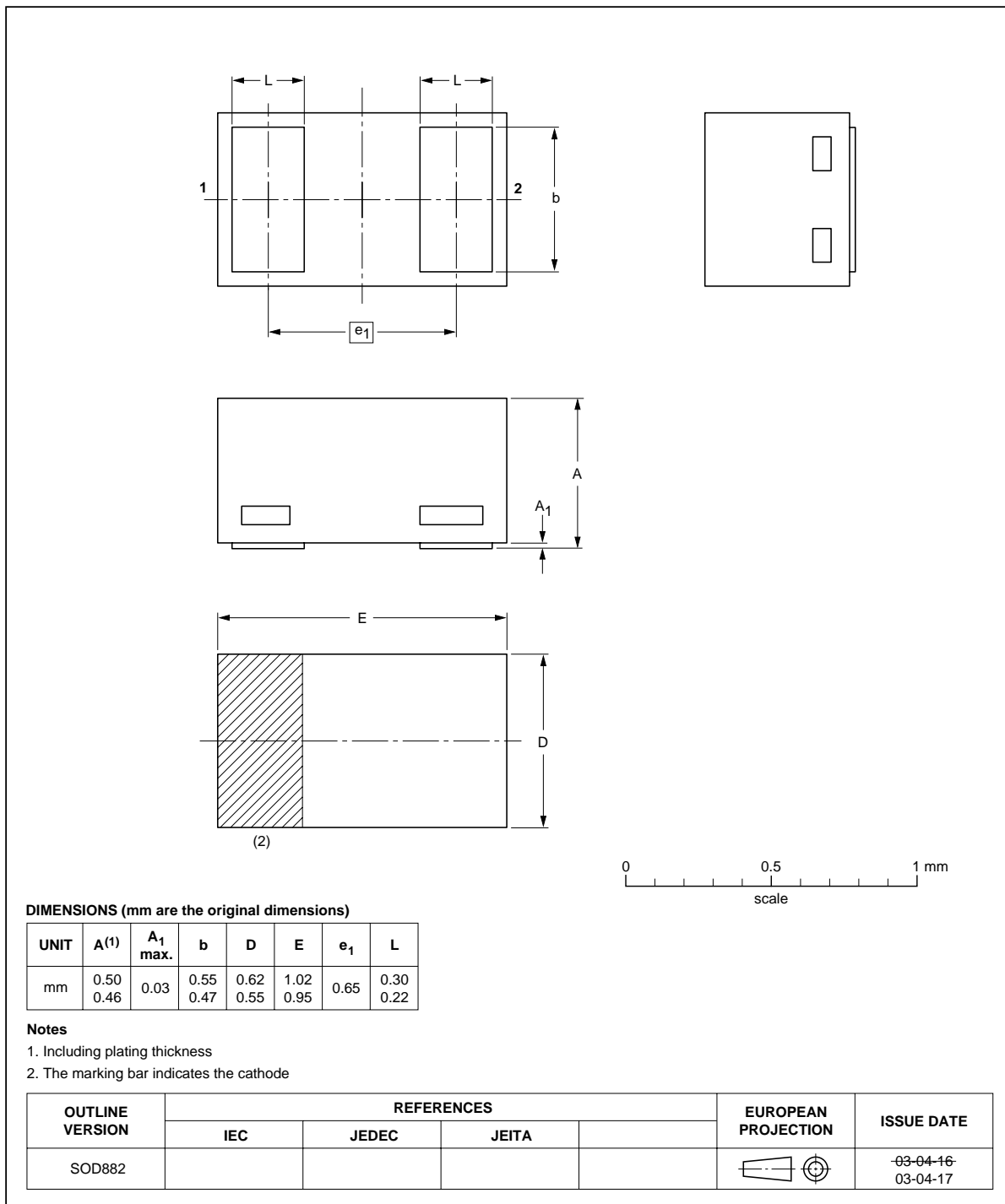


Fig 4. Package outline.



9. Revision history

Table 8: Revision history

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
PMEG2005AEL_2	20040427	Product data	-	9397 750 13201	PMEG2005AEL_1
Modifications:		• General description changed.			
PMEG2005AEL_1	20040419	Product data	-	9397 750 12465	-

10. Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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14. Contents

1	Product profile	1
1.1	General description.	1
1.2	Features	1
1.3	Applications	1
1.4	Quick reference data.	1
2	Pinning information	2
3	Ordering information	2
4	Marking	2
5	Limiting values	2
6	Thermal characteristics	3
7	Characteristics	3
8	Package outline	5
9	Revision history	6
10	Data sheet status	7
11	Definitions	7
12	Disclaimers	7
13	Contact information	7



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